

DP-308655

ABSTRACT OF THE DISCLOSURE

A circuit assembly comprising a substrate formed to have one or more apertures that define one or more compliant members in the substrate, and to which a circuit device can be attached so as to reduce thermally-induced stresses in the device and in solder joints securing the device to the substrate. The compliant members are sufficiently compliant to permit relatively large surface-mount devices to be attached to an organic substrate without sacrificing reliability.